

Title (en)

Polishing machine with a tensioned finishing belt and an improved work supporting head.

Title (de)

Poliermaschine mit einem gespannten Feinschleifband und einem verbesserten Werkstückträgerkopf.

Title (fr)

Machine de polissage à bande microabrasive tendue et à tête support de plaquette perfectionnée.

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Application

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Priority

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Abstract (en)

The machine according to the invention comprises a microabrasive belt (33) tensioned above a planar reference platform (30) between a feeding spool and a receiving spool (50), and a head (32) for supporting a specimen (44) comprising a rigid part (140) and a disc (142) made of a flexible material and capable of holding the face of the specimen (44) to be polished opposite the abrasive belt. Application to the polishing of silicon plates (wafers) containing integrated components, in particular magnetic read and write heads. <IMAGE>

IPC 1-7

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IPC 8 full level

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Citation (search report)

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- [Y] PATENT ABSTRACTS OF JAPAN vol. 8, no. 83 (M-290)(1520) 17 Avril 1984 & JP-A-59 001 151 (HITACHI SEISAKUSHO K.K.) 6 Janvier 1984
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